

TWSE

7769

INVESTOR PRESENTATION

Hosted by Taiwan Stock Exchange (TWSE)

(2026/04/30)



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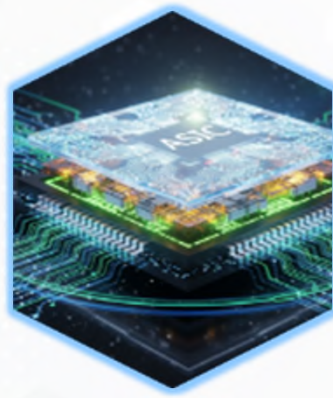
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AGENDA



01

Operation Update



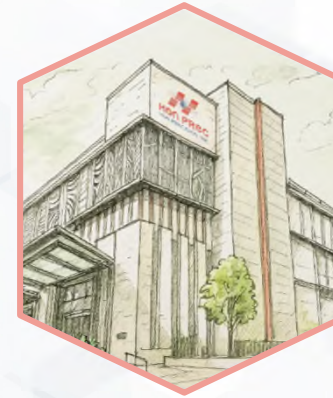
02

Growth Drivers



03

Profitability



04

ESG



Operation Update

- Key Requirement
- 2026 Capacity Expansion Plan
- Order Mix
- Geographic Mix: Shipment vs. End Market



2026 Capacity Expansion Plan

2026 ANNUAL CAPACITY FORECAST



Total Workforce
2026+50%



Floor Space
2026+25%



Procurement
2026+40%

(set)

3000

2500

2000

1500

1000

500

0

2025

2026 E (as of 25Q3)

2026 E (as of 26Q1)

YoY **40%**

Capacity **+30%**

Capacity **+10%**

Order Mix



AI
HPC
ASIC

2025 2026Q1
72% ▶ 78%

- ▶ AI Computing
- ▶ Server
- ▶ Networking
- ▶ APU/GPU/CPU/FPGA



Automotive

2025 2026Q1
11% ▶ 9%

- ▶ Sensor
- ▶ MCU
- ▶ LiDAR



Mobile AP
Communication

2025 2026Q1
10% ▶ 9%

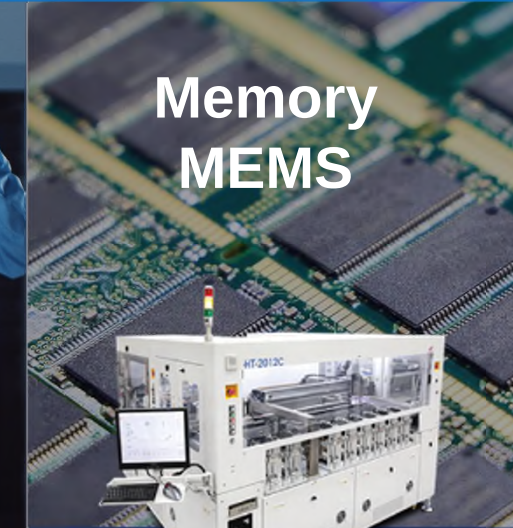
- ▶ SiP
- ▶ 5G OTA
- ▶ Power, PMIC
- ▶ Mobile Phone/AP
- ▶ RF Related Devices



3C
Consumer

2025 2026Q1
5% ▶ 3%

- ▶ AR glasses
- ▶ LCD driver
- ▶ CIS



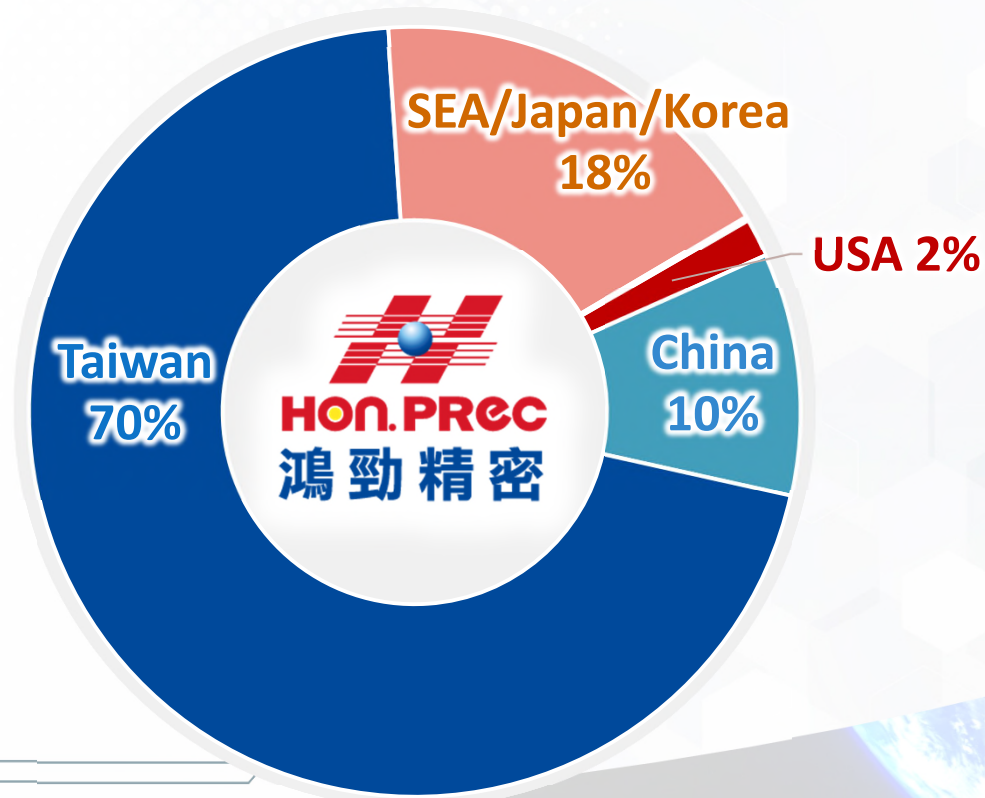
Memory
MEMS

2025 2026Q1
2% ▶ 1%

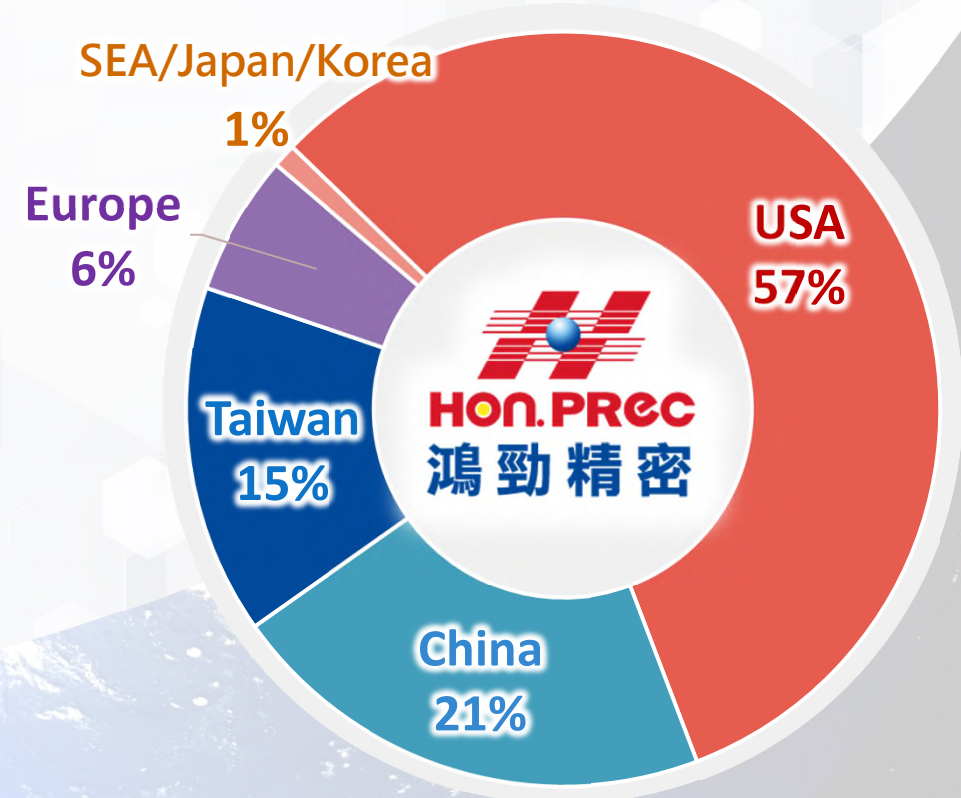
- ▶ Flash/DRAM Memory
- ▶ Accelerometer
- ▶ Gyroscope
- ▶ Barometer
- ▶ Light Sensor
- ▶ Pressure Sensor

Geographic Mix : Shipment & End Customer

Shipment Location



End Customer Mix

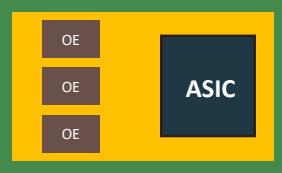
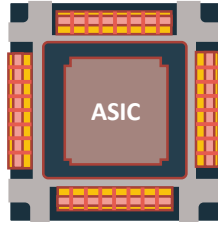
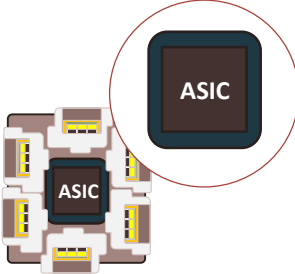
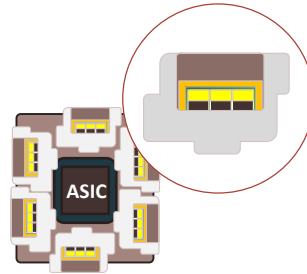


Growth Drivers

- CPO
- High-End FT ATC Handler Growth Driver
- New Release For Final Test (FT)
- High-End SLT Handler Strengths
- New Release For System Level IC Test (SLT)
- Active Thermal Control (ATC) Roadmap
- Cold Plate

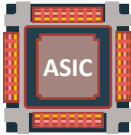
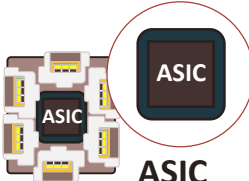
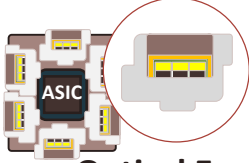
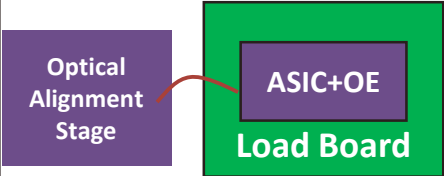
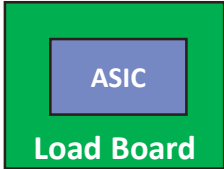
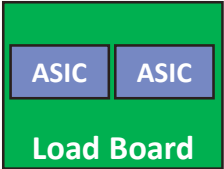


CPO Test Insertions

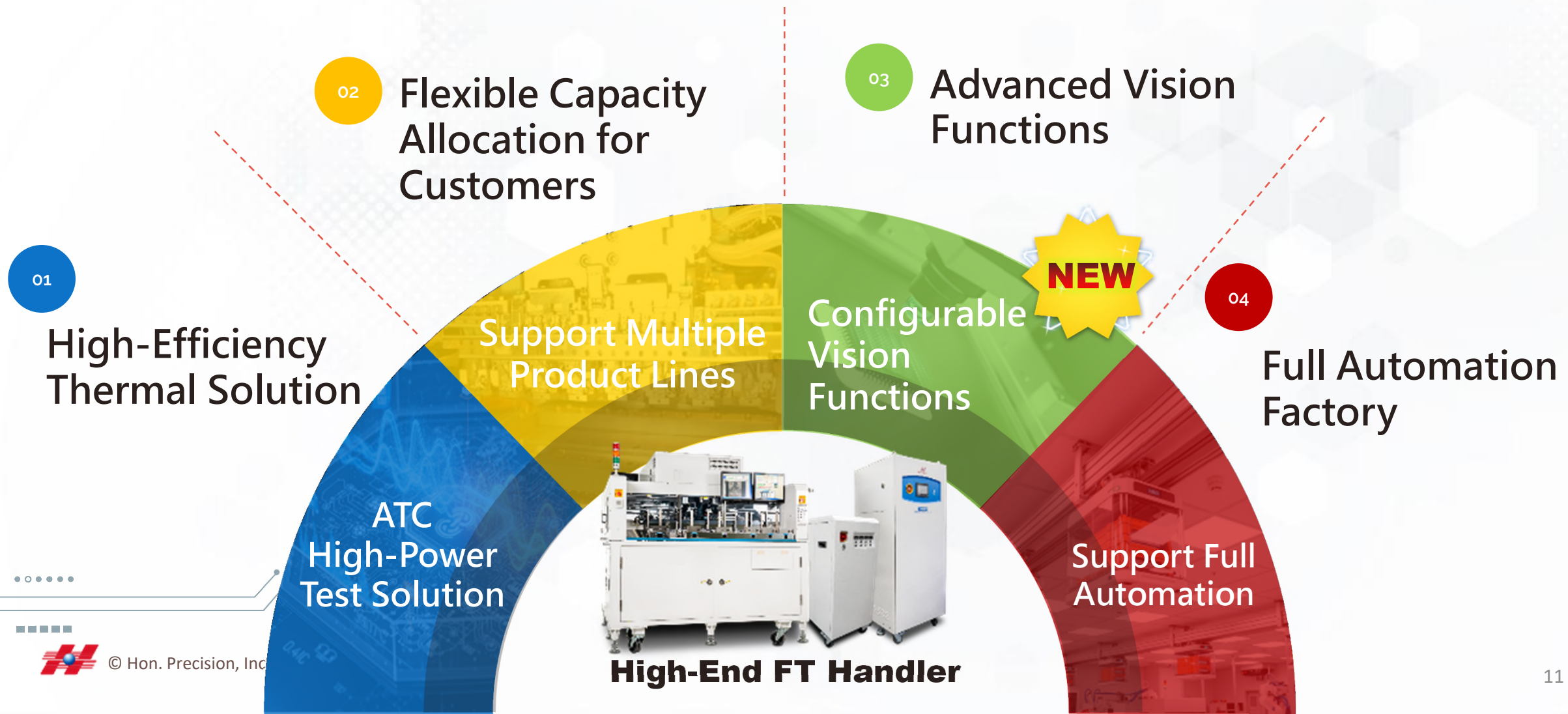
Test Insertion	Insertion 1	Insertion 2	Insertion 3	Insertion 4	CPO FT		
				Joint Development	Mass Production		
Test Content							
	PIC	EIC-PIC	Optical Engine	ASIC + Optical Engine	ASIC + Optical Engine	ASIC	Optical Engine
	Wafer Level (Foundry)	Wafer Level (Foundry)	DIE/Chip Level (OSAT)	Package-Level(OSAT)			
				O/E	E/E	E/E	E/E
HON.PREC Test Equipment	NA			ATE Tester + ATC (3KW) Handler	ATE Tester + ATC (2KW) Handler	ATE Tester + ATC (1KW) Handler	ATE Tester + ATC (1KW) Handler



CPO Insertion 4 and FT

Test Insertion	Insertion 4	CPO FT		
	Joint Development	Mass Production		
Test Content	 ASIC + Optical Engine	 ASIC + Optical Engine	 ASIC	 Optical Engine
	O/E	E/E	E/E	E/E
HON.PREC Test Equipment	ATE Tester + ATC Handler			
	3000W	2000W	1000W	1000W
	Single Site	Single Site	Single/Dual/Quad Site	Dual Site
			  	

High-End FT ATC Handler Growth Driver



New Release For Final Test (FT)

CPO FT



- O/E by ATE Tester
- Insertion 4
- Optical Engine & ASIC

Large Package



- 380X380 mm (Tray spec)
- 2000 kg contact force
- Support ATC System
- Support Full Automation

MC Lid Handler



- Co-development with partners
- In-house Designed Machine Platform and ATC system

WMCM Package



- Support ATC System (3000W)
- 8 / 16 sites

Top/Bottom AOI



- Top/Bottom AOI
- Current: 2D / Next: 3D

Hybrid Cooling Handler



- Switchable Cooling (Air/Liquid/Refrigerant ATC)
- Air Cooling(16 sites)
- Liquid Cooling(High power)

High-End SLT Handler Strengths



New Release For System Level IC Test (SLT)

Tri-Temp SLT



- -70°C~175°C (3000W)
- Support 6/812/20 sites

MSLT



- Full Automation
- 36~192 sites

ASIC SLT



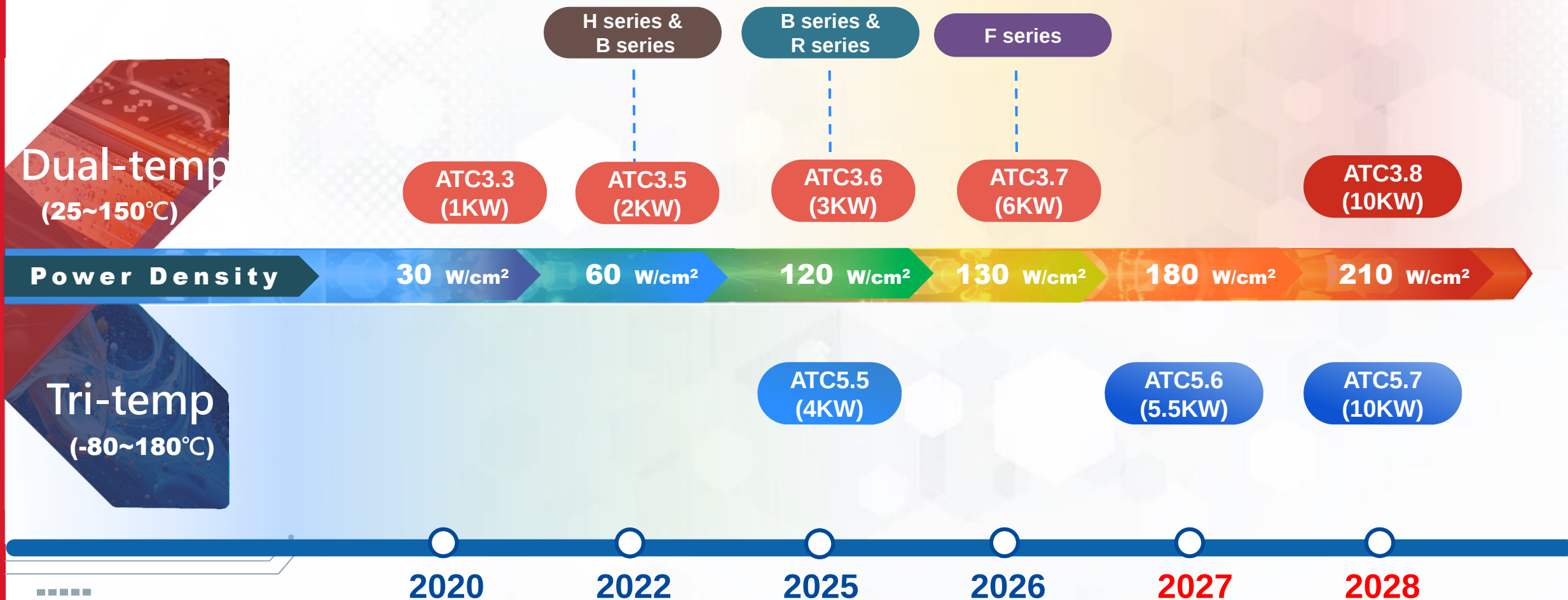
- 25°C~150°C (3000W)
- Support 6/12/24/36 sites

CPO OE SLT



- O/O Test

Active Thermal Control (ATC) Roadmap



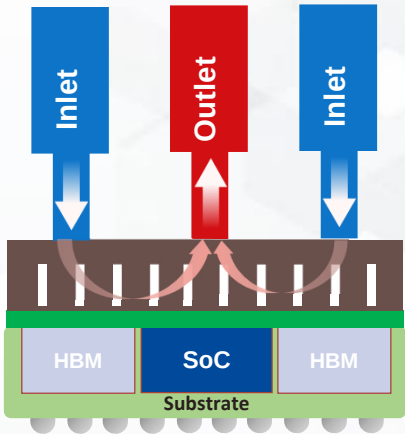
Cold Plate

Micro Channel Cold Plate

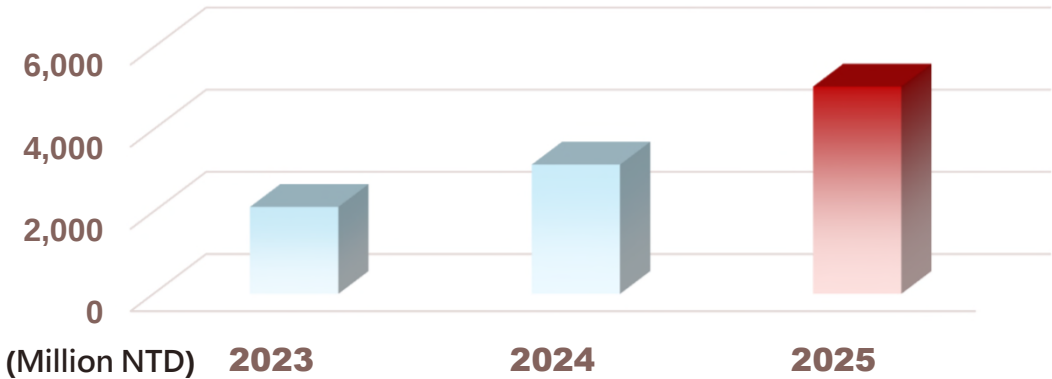
	Fin Cold Plate	MCCP
Channel Size	500um	150~200um
Power Density	55W/cm2	120W/cm2
Response Time	7s	3s



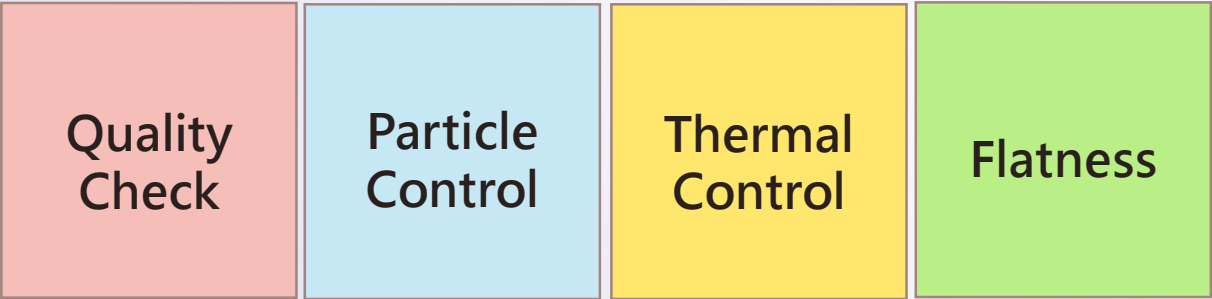
Micro Channel Lid



Sales Revenue



Machine Capability



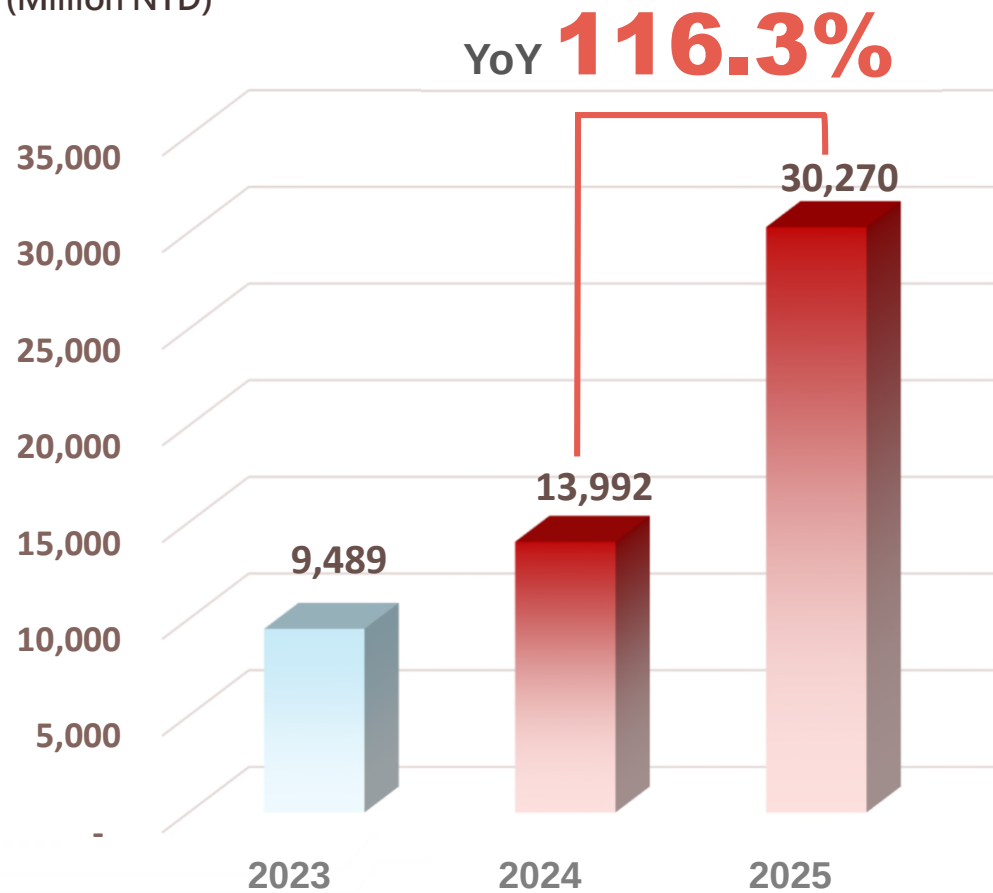
Profitability

- Revenue Trend
- Gross Margin Trend
- Net Profit & EPS
- R&D Intensity

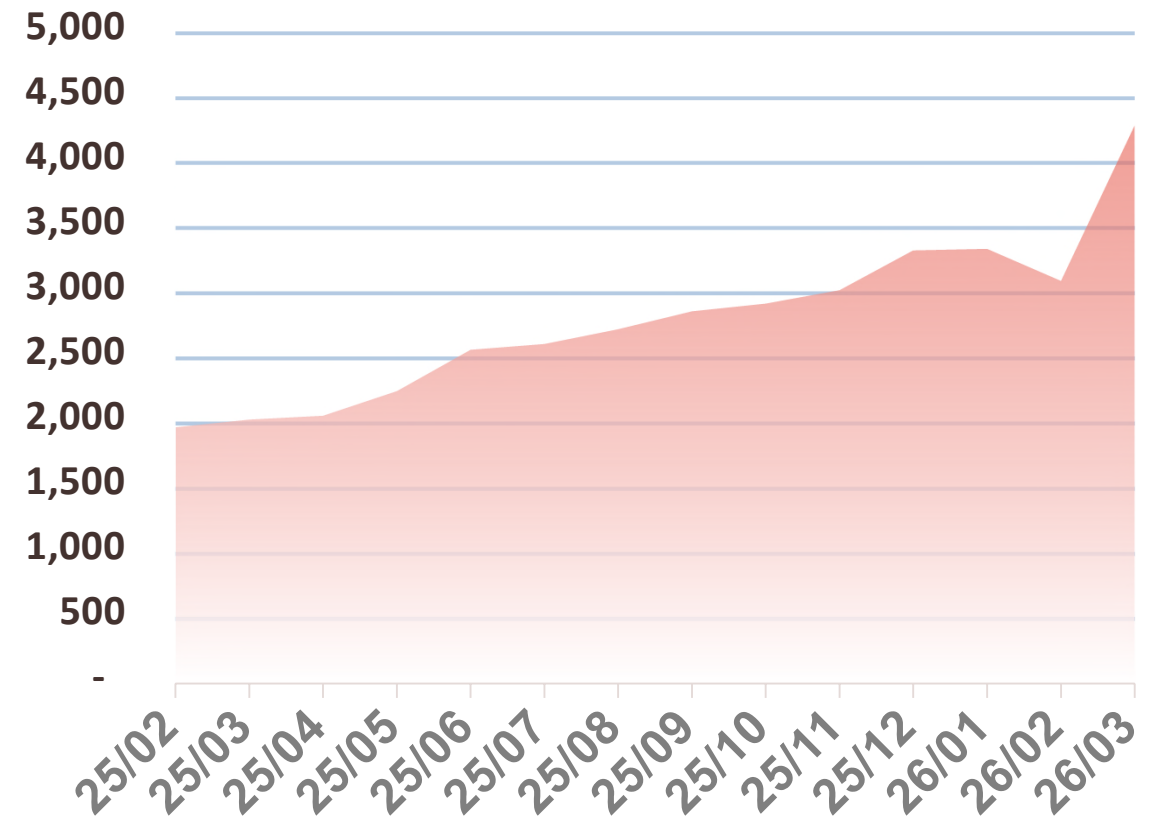


Revenue Trend

(Million NTD)

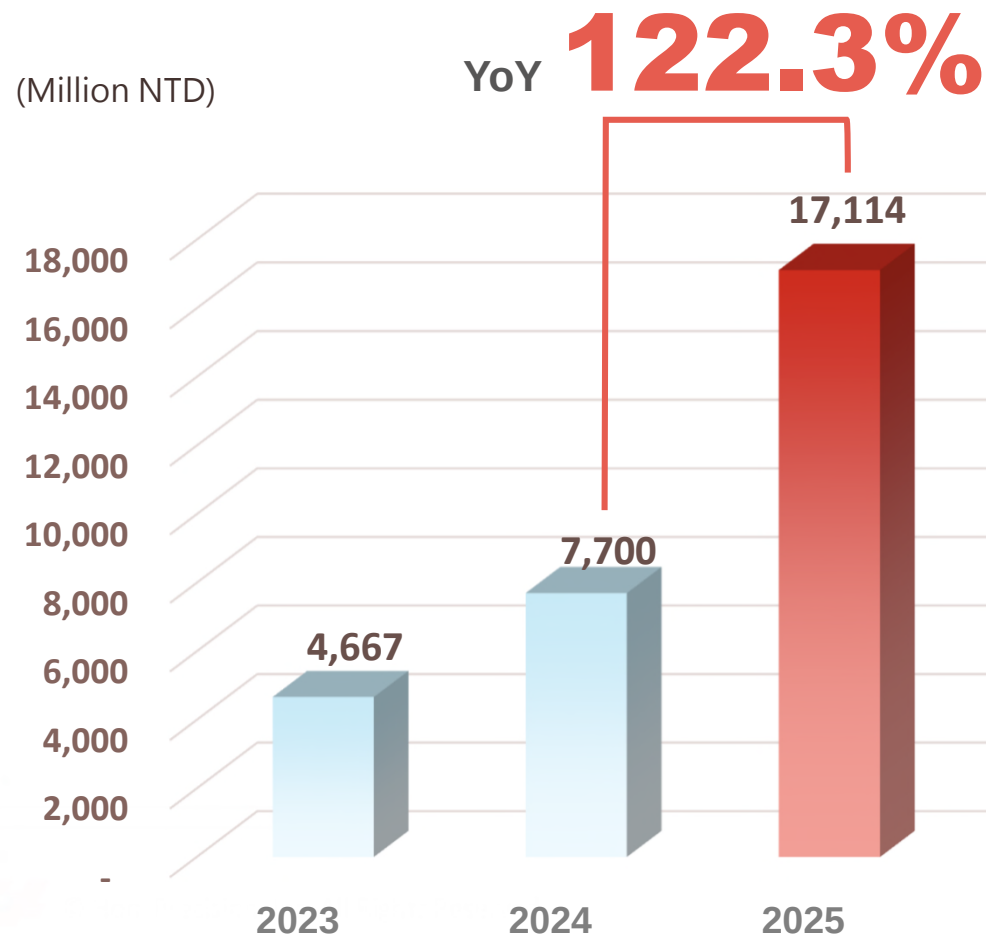


(Million NTD)

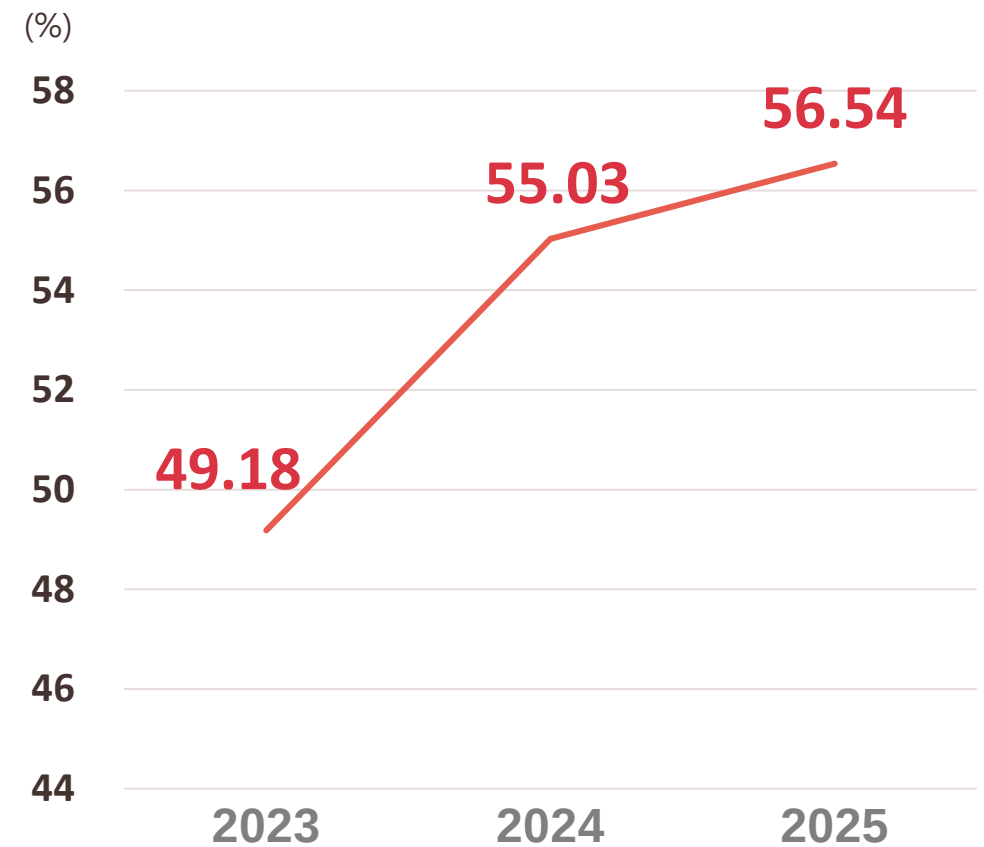


Gross Margin Trend

Gross Profit

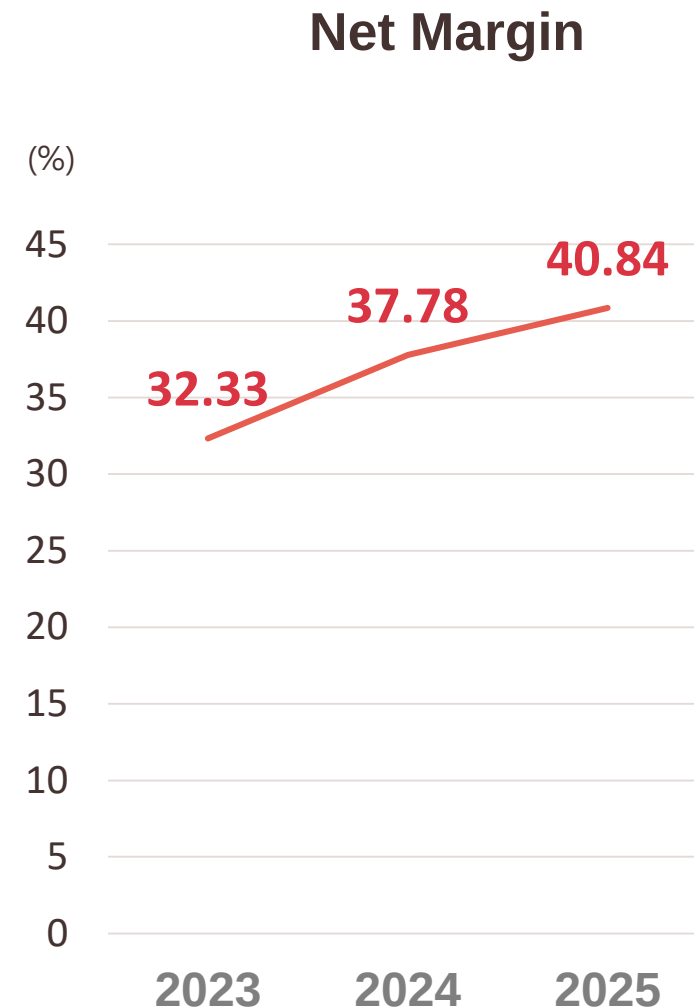
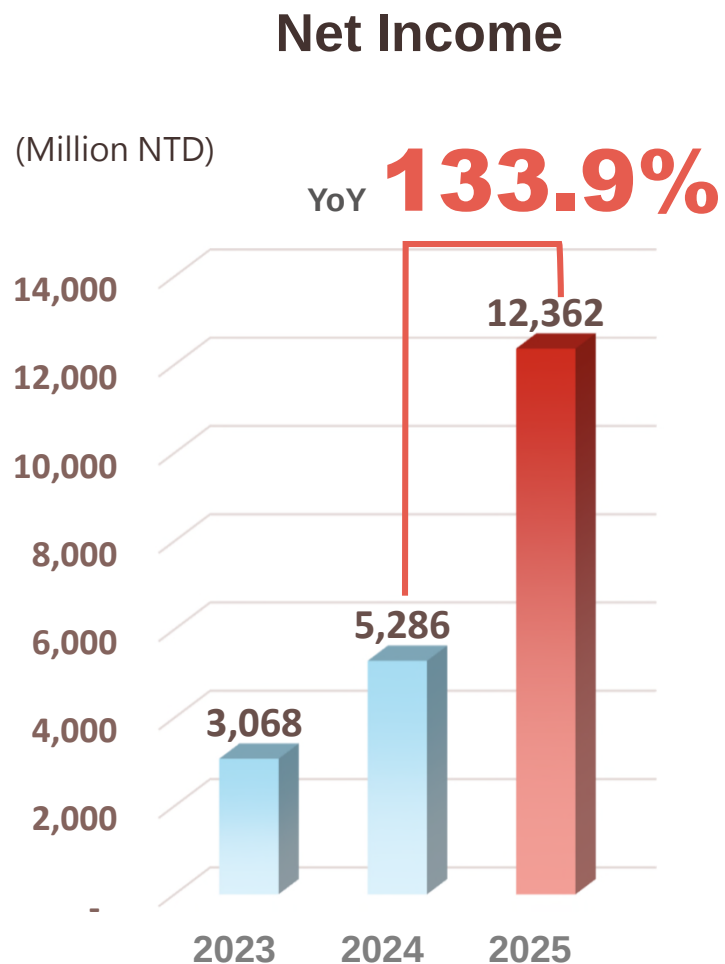


Gross Margin

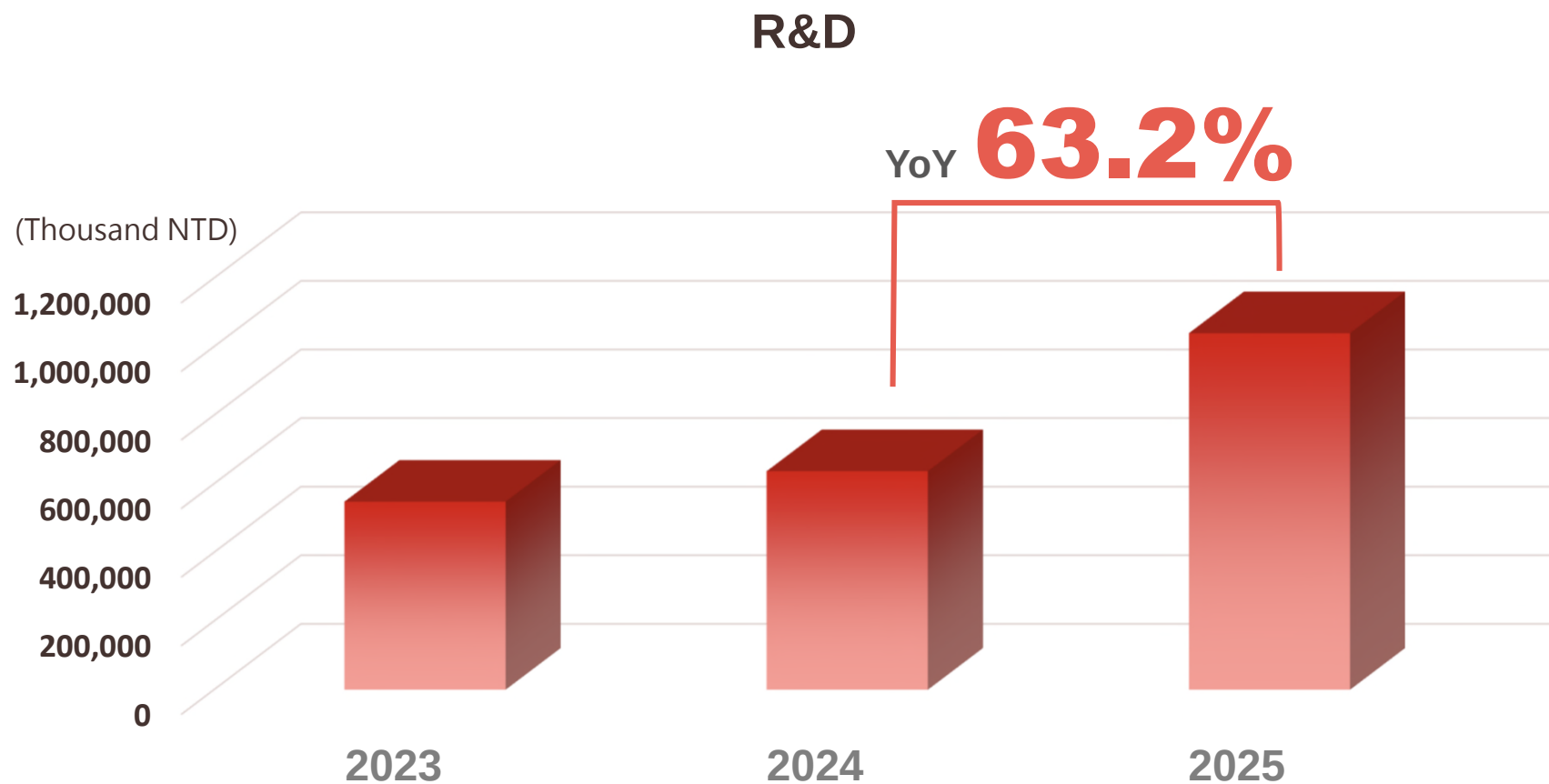


Net Profit & EPS

	EPS (NT\$)	Weighted Average Shares (in thousands)
2025	75.71	163,289
2024	32.95	160,446
2023	19.17	160,000

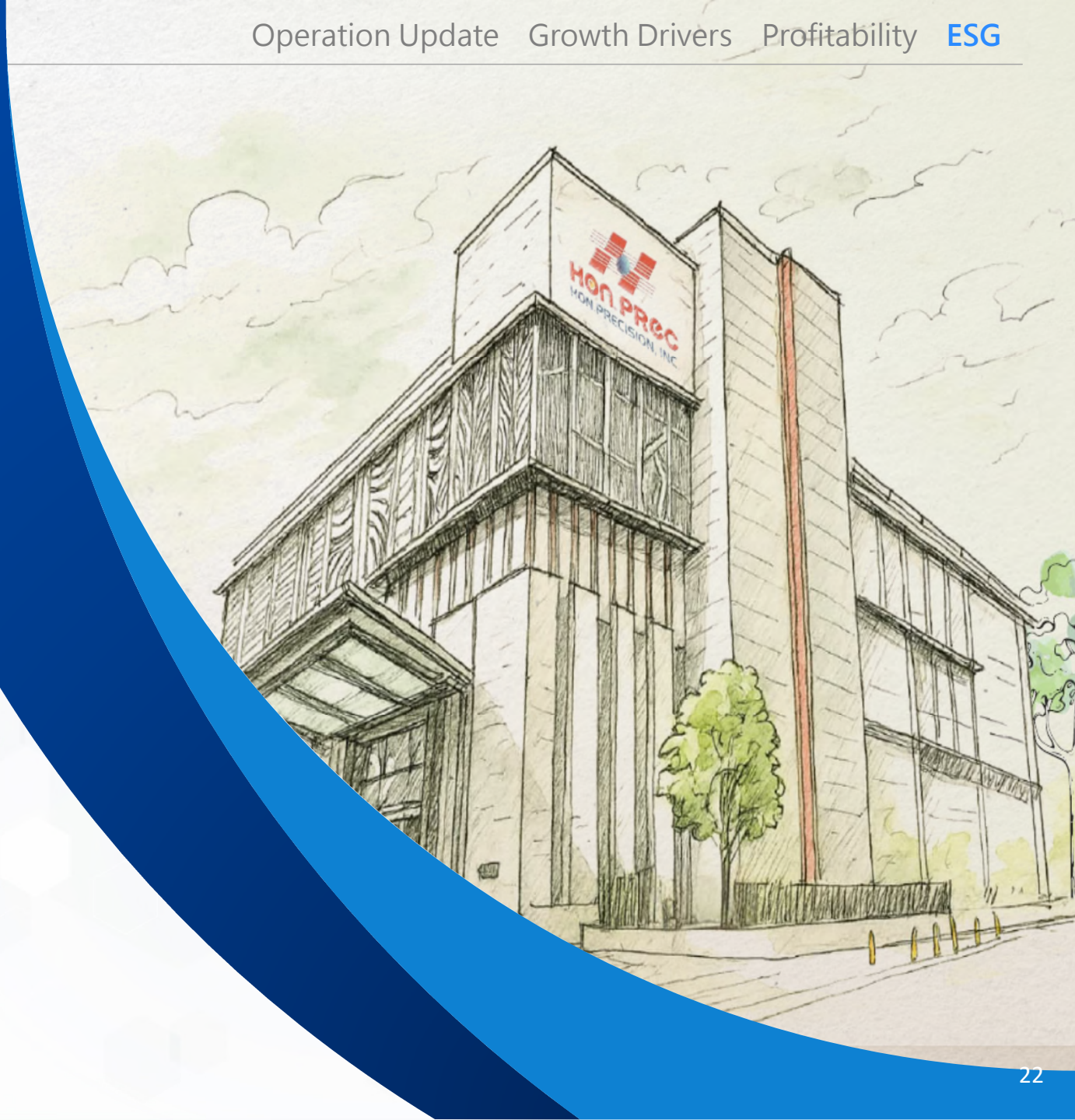


R&D Intensity



ESG

- ESG Strategy
- ESG Report Timeline



ESG Strategy



Environment

- Install solar panels to increase the use of renewable energy
- Implement environmental safety policies to ensure environmental protection
- Promote low-carbon supply chain to reduce carbon footprint
- ISO 14064 greenhouse gas verification



Governance

- Establish functional committees to enhance governance efficiency
- Strengthen corporate governance policies and systems



Social

- Support disadvantaged groups and participate in public welfare activities
- Promote sports and healthy lifestyles
- Build a positive workplace culture
- ISO 45001 occupational safety certification
- **Establish Hon Precision Public Charity Foundation(26Q1)**



ESG Report Timeline

ESG Report TIMELINE



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Preliminary Data
Collection Preparation

Materiality Assessment

Interviews &
Data Consolidation

Report Writing

- Collection of Sustainability Topics and Identification of Positive & Negative Impacts
- Stakeholder Identification
- Collection of Climate-related Financial Disclosures

- Questionnaire Distribution & Collection
- Materiality Matrix Analysis
- Material Topics Determination

- Department Interviews and Quantitative Data Collection
- Compilation of Quantitative Data

- Completion and Publication of ESG Report

DONE

3/9 ~ 4/15

4/16~5/15

5/16~5/31

Smarter Chips. Efficient Tomorrow.

Powered by Our Growth Drivers.

Questions & Answers

